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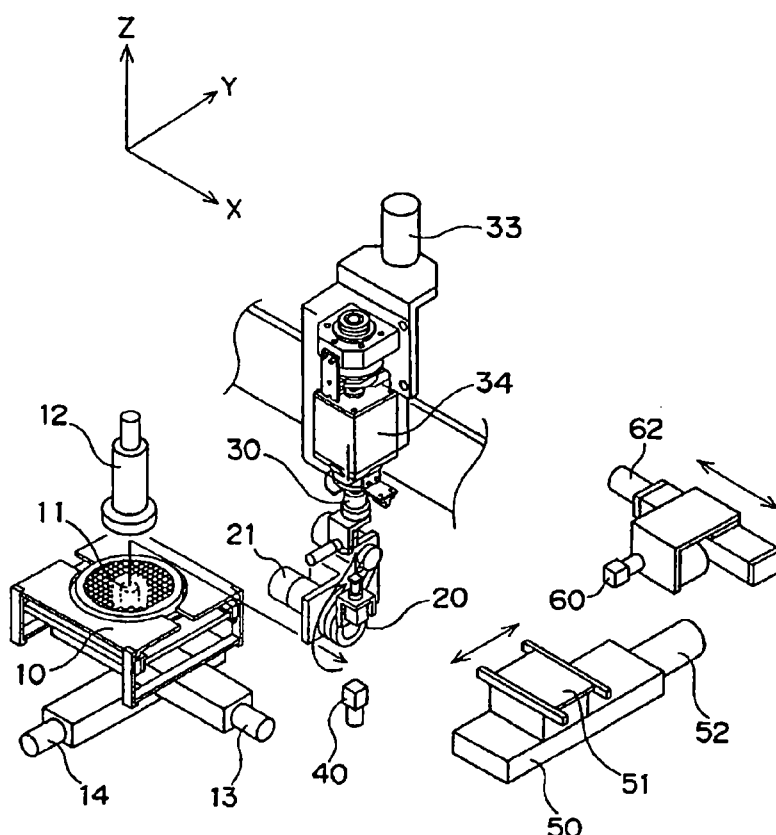
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(54) Title: APPARATUS AND METHOD FOR MOUNTING COMPONENT



(57) Abstract: A component mounting system includes first to third (pickup, transfer, and placement) stations. A component supplied at the component supply is picked up by a transport head at the pickup station and then transferred to a placement head at the transfer station. The placement head carries the component to the placement station where the component is placed and mounted on a substrate such as circuit board. The component held by the placement head is recognized by an imaging device at or in the vicinity of the transfer station.

WO 01/72097 A3



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